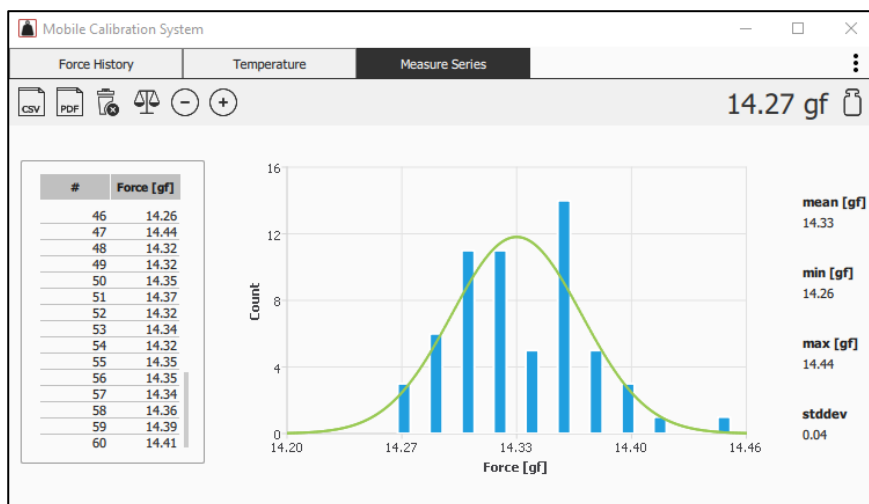




Mobile Calibration System 20

The MCS-20 offers bond force calibration for bond weights up to 2,500 gf (2.450 cN).

The software-supported calibration enables the observation of force overtime as well as the observation of temperature overtime. CSV and PDF files can be exported to document the results.



With the **Mobile Calibration System** from **F&S BONDTEC**, easy and quick calibration of bond forces gets possible.

The calibration system can be used best with Bondstar Software Version 2.7, to automatically calibrate the bond force without operator interferences. With older Bondstar software releases, or bonders from third-party manufacturers, the calibration system can also be used stand-alone with a conventional Windows PC. The **MCS-20** is therefore interesting for every user who wants to measure or calibrate a vertical force.

The temperature profile of the substrate or component holder is recorded by an external temperature sensor. The temperatures are determined and compensation can be carried out this way.

Due to the compact design, the unit can be assembled and disassembled quickly. The MCS-20 is operated via USB and can therefore be used on classic PCs or directly on our bonders. The measuring itself can be done on battery power as well.

The software can also be used to perform a MCA (machine capability analysis) for the bond force. The results can be exported in .CSV and .PDF formats.

The operation of the software can be learned intuitively within minutes.

Product characteristics

- [Bond Weight Calibration System Thin Wire / MCS-20 \(1 lb / 450 g\)](#)
- [Bond Weight Calibration System Heavy Wire / MCS-20 \(10 lb / 4.5 kg\)](#)

System requirements

Calibration system	Windows 7 or higher
	Open GL 3 or higher
	100MB free hard disk space

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